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Details

Product Status	Active
Core Processor	HC08
Core Size	8-Bit
Speed	8MHz
Connectivity	-
Peripherals	LVD, POR, PWM
Number of I/O	5
Program Memory Size	4KB (4K x 8)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	128 x 8
Voltage - Supply (Vcc/Vdd)	2.7V ~ 5.5V
Data Converters	A/D 4x8b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 125°C (TA)
Mounting Type	Through Hole
Package / Case	8-DIP (0.300", 7.62mm)
Supplier Device Package	8-PDIP
Purchase URL	https://www.e-xfl.com/pro/item?MUrl=&PartUrl=mc68hc908qt4mpe

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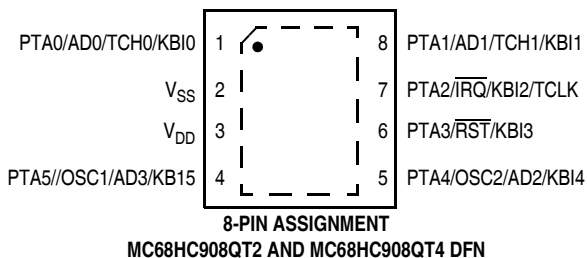
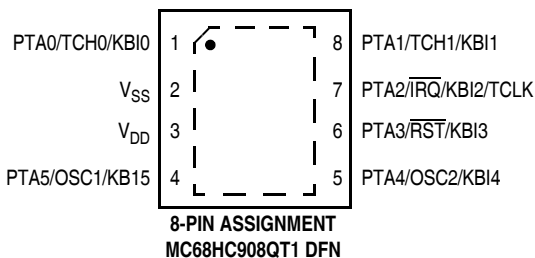
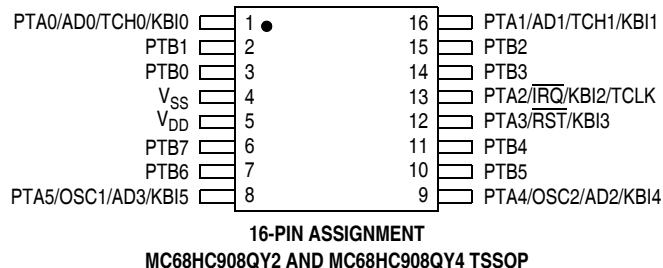
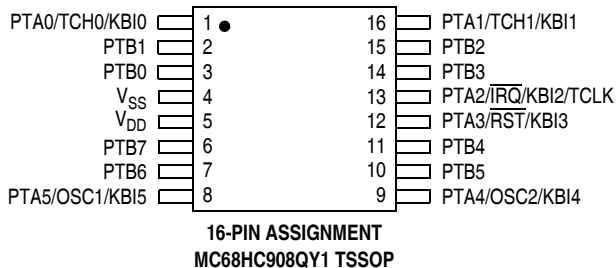
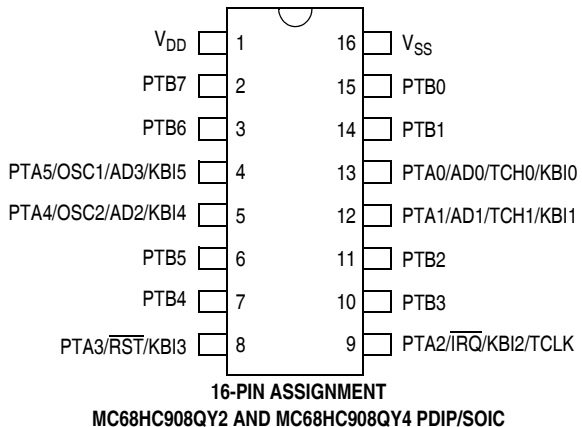
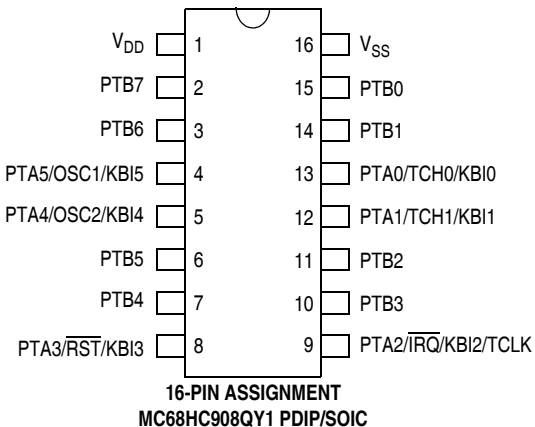
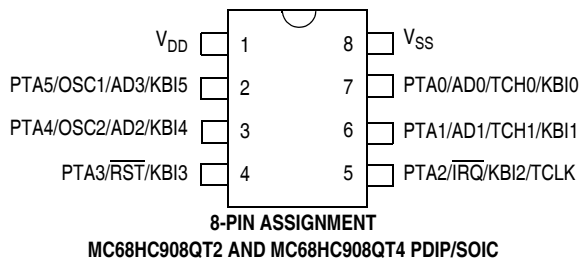
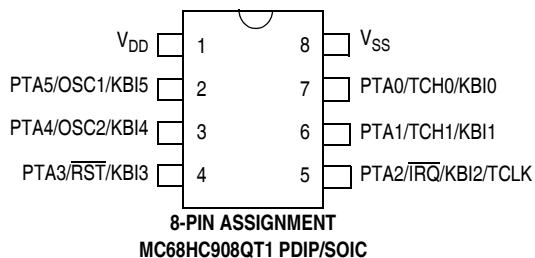


Figure 1-2. MCU Pin Assignments

1.5 Pin Functions

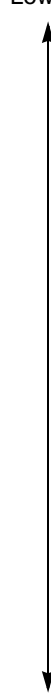
Table 1-2 provides a description of the pin functions.

Table 1-2. Pin Functions

Pin Name	Description	Input/Output
V _{DD}	Power supply	Power
V _{SS}	Power supply ground	Power
PTA0	PTA0 — General purpose I/O port	Input/Output
	AD0 — A/D channel 0 input	Input
	TCH0 — Timer Channel 0 I/O	Input/Output
	KBI0 — Keyboard interrupt input 0	Input
PTA1	PTA1 — General purpose I/O port	Input/Output
	AD1 — A/D channel 1 input	Input
	TCH1 — Timer Channel 1 I/O	Input/Output
	KBI1 — Keyboard interrupt input 1	Input
PTA2	PTA2 — General purpose input-only port	Input
	\overline{IRQ} — External interrupt with programmable pullup and Schmitt trigger input	Input
	KBI2 — Keyboard interrupt input 2	Input
	TCLK — Timer clock input	Input
PTA3	PTA3 — General purpose I/O port	Input/Output
	\overline{RST} — Reset input, active low with internal pullup and Schmitt trigger	Input
	KBI3 — Keyboard interrupt input 3	Input
PTA4	PTA4 — General purpose I/O port	Input/Output
	OSC2 — XTAL oscillator output (XTAL option only) RC or internal oscillator output (OSC2EN = 1 in PTAPUE register)	Output Output
	AD2 — A/D channel 2 input	Input
	KBI4 — Keyboard interrupt input 4	Input
PTA5	PTA5 — General purpose I/O port	Input/Output
	OSC1 — XTAL, RC, or external oscillator input	Input
	AD3 — A/D channel 3 input	Input
	KBI5 — Keyboard interrupt input 5	Input
PTB[0:7] ⁽¹⁾	8 general-purpose I/O ports	Input/Output

1. The PTB pins are not available on the 8-pin packages (see note in [12.1 Introduction](#)).

Table 2-1. Vector Addresses

Vector Priority	Vector	Address	Vector
Lowest  Highest	IF15	\$FFDE	ADC conversion complete vector (high)
		\$FFDF	ADC conversion complete vector (low)
	IF14	\$FFE0	Keyboard vector (high)
		\$FFE1	Keyboard vector (low)
	IF13 ↓ IF6	—	Not used
	IF5	\$FFF2	TIM overflow vector (high)
		\$FFF3	TIM overflow vector (low)
	IF4	\$FFF4	TIM Channel 1 vector (high)
		\$FFF5	TIM Channel 1 vector (low)
	IF3	\$FFF6	TIM Channel 0 vector (high)
		\$FFF7	TIM Channel 0 vector (low)
	IF2	—	Not used
	IF1	\$FFFA	$\overline{\text{IRQ}}$ vector (high)
		\$FFFB	$\overline{\text{IRQ}}$ vector (low)
	—	\$FFFC	SWI vector (high)
		\$FFFD	SWI vector (low)
	—	\$FFFE	Reset vector (high)
		\$FFFF	Reset vector (low)

2.5 Random-Access Memory (RAM)

Addresses \$0080–\$00FF are RAM locations. The location of the stack RAM is programmable. The 16-bit stack pointer allows the stack to be anywhere in the 64-Kbyte memory space.

NOTE

For correct operation, the stack pointer must point only to RAM locations.

Before processing an interrupt, the central processor unit (CPU) uses five bytes of the stack to save the contents of the CPU registers.

NOTE

For M6805, M146805, and M68HC05 compatibility, the H register is not stacked.

During a subroutine call, the CPU uses two bytes of the stack to store the return address. The stack pointer decrements during pushes and increments during pulls.

NOTE

Be careful when using nested subroutines. The CPU may overwrite data in the RAM during a subroutine or during the interrupt stacking operation.

Auto Wakeup Module (AWU)

Bits 7–4 — Not used

These read-only bits always read as 0s.

KEYF — Keyboard Flag Bit

This read-only bit is set when a keyboard interrupt is pending on port A or auto wakeup. Reset clears the KEYF bit.

- 1 = Keyboard/auto wakeup interrupt pending
- 0 = No keyboard/auto wakeup interrupt pending

ACKK — Keyboard Acknowledge Bit

Writing a 1 to this write-only bit clears the keyboard/auto wakeup interrupt request on port A and auto wakeup logic. ACKK always reads as 0. Reset clears ACKK.

IMASKK — Keyboard Interrupt Mask Bit

Writing a 1 to this read/write bit prevents the output of the keyboard interrupt mask from generating interrupt requests on port A or auto wakeup. Reset clears the IMASKK bit.

- 1 = Keyboard/auto wakeup interrupt requests masked
- 0 = Keyboard/auto wakeup interrupt requests not masked

NOTE

MODEK is not used in conjunction with the auto wakeup feature. To see a description of this bit, see [9.7.1 Keyboard Status and Control Register](#).

4.6.3 Keyboard Interrupt Enable Register

The keyboard interrupt enable register (KBIER) enables or disables the auto wakeup to operate as a keyboard/auto wakeup interrupt input.

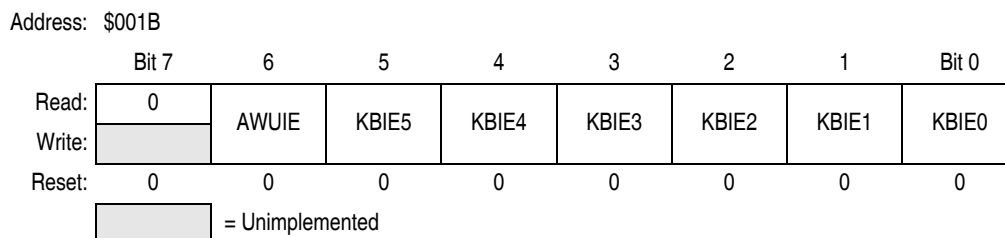


Figure 4-4. Keyboard Interrupt Enable Register (KBIER)

AWUIE — Auto Wakeup Interrupt Enable Bit

This read/write bit enables the auto wakeup interrupt input to latch interrupt requests. Reset clears AWUIE.

- 1 = Auto wakeup enabled as interrupt input
- 0 = Auto wakeup not enabled as interrupt input

NOTE

KBIE5–KBIE0 bits are not used in conjunction with the auto wakeup feature. To see a description of these bits, see [9.7.2 Keyboard Interrupt Enable Register](#).

Configuration Register (CONFIG)

IRQPUD — $\overline{\text{IRQ}}$ Pin Pullup Control Bit

- 1 = Internal pullup is disconnected
- 0 = Internal pullup is connected between $\overline{\text{IRQ}}$ pin and V_{DD}

IRQEN — $\overline{\text{IRQ}}$ Pin Function Selection Bit

- 1 = Interrupt request function active in pin
- 0 = Interrupt request function inactive in pin

OSCOPT1 and OSCOPT0 — Selection Bits for Oscillator Option

- (0, 0) Internal oscillator
- (0, 1) External oscillator
- (1, 0) External RC oscillator
- (1, 1) External XTAL oscillator

RSTEN — $\overline{\text{RST}}$ Pin Function Selection

- 1 = Reset function active in pin
- 0 = Reset function inactive in pin

NOTE

The RSTEN bit is cleared by a power-on reset (POR) only. Other resets will leave this bit unaffected.

Address: \$001F

	Bit 7	6	5	4	3	2	1	Bit 0
Read:	COPRS	LVISTOP	LVIRSTD	LVIPWRD	LVI5OR3	SSREC	STOP	COPD
Write:								
Reset:	0	0	0	0	U	0	0	0
POR:	0	0	0	0	0	0	0	0

U = Unaffected

Figure 5-2. Configuration Register 1 (CONFIG1)

COPRS (Out of STOP Mode) — COP Reset Period Selection Bit

- 1 = COP reset short cycle = $8176 \times \text{BUSCLKX4}$
- 0 = COP reset long cycle = $262,128 \times \text{BUSCLKX4}$

COPRS (In STOP Mode) — Auto Wakeup Period Selection Bit

- 1 = Auto wakeup short cycle = $512 \times \text{INTRCOSC}$
- 0 = Auto wakeup long cycle = $16,384 \times \text{INTRCOSC}$

LVISTOP — LVI Enable in Stop Mode Bit

When the LVIPWRD bit is clear, setting the LVISTOP bit enables the LVI to operate during stop mode. Reset clears LVISTOP.

- 1 = LVI enabled during stop mode
- 0 = LVI disabled during stop mode

LVIRSTD — LVI Reset Disable Bit

LVIRSTD disables the reset signal from the LVI module.

- 1 = LVI module resets disabled
- 0 = LVI module resets enabled

10.4 LVI Status Register

The LVI status register (LVISR) indicates if the V_{DD} voltage was detected below the V_{TRIPF} level while LVI resets have been disabled.

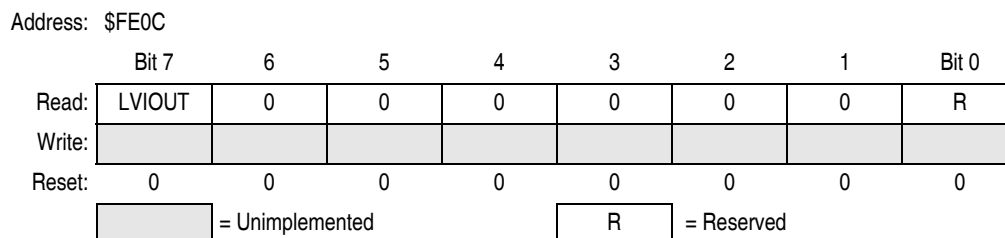


Figure 10-2. LVI Status Register (LVISR)

LVIOUT — LVI Output Bit

This read-only flag becomes set when the V_{DD} voltage falls below the V_{TRIPF} trip voltage and is cleared when V_{DD} voltage rises above V_{TRIPR} . The difference in these threshold levels results in a hysteresis that prevents oscillation into and out of reset (see [Table 10-1](#)). Reset clears the LVIOUT bit.

Table 10-1. LVIOUT Bit Indication

V_{DD}	LVIOUT
$V_{DD} > V_{TRIPR}$	0
$V_{DD} < V_{TRIPF}$	1
$V_{TRIPF} < V_{DD} < V_{TRIPR}$	Previous value

10.5 LVI Interrupts

The LVI module does not generate interrupt requests.

10.6 Low-Power Modes

The STOP and WAIT instructions put the MCU in low power-consumption standby modes.

10.6.1 Wait Mode

If enabled, the LVI module remains active in wait mode. If enabled to generate resets, the LVI module can generate a reset and bring the MCU out of wait mode.

10.6.2 Stop Mode

When the LVIPWRD bit in the configuration register is cleared and the LVISTOP bit in the configuration register is set, the LVI module remains active in stop mode. If enabled to generate resets, the LVI module can generate a reset and bring the MCU out of stop mode.

11.3.1.1 Internal Oscillator Trimming

The 8-bit trimming register, OSCTRIM, allows a clock period adjust of +127 and –128 steps. Increasing OSCTRIM value increases the clock period. Trimming allows the internal clock frequency to be set to 12.8 MHz \pm 5%.

All devices are factory programmed with trim values in reserved FLASH memory locations \$FFC0 and \$FFC1. The trim value is not automatically loaded into the OSCTRIM register. User software must copy the trim value from \$FFC0 or \$FFC1 into OSCTRIM if needed. The factory trim value provides the accuracy required for communication using forced monitor mode. Some production programmers erase the factory trim values, so confirm with your programmer vendor that the trim values at \$FFC0 and \$FFC1 are preserved, or are re-trimmed. Trimming the device in the user application board will provide the most accurate trim value.

11.3.1.2 Internal to External Clock Switching

When external clock source (external OSC, RC, or XTAL) is desired, the user must perform the following steps:

1. For external crystal circuits only, OSCOPT[1:0] = 1:1: To help precharge an external crystal oscillator, set PTA4 (OSC2) as an output and drive high for several cycles. This may help the crystal circuit start more robustly.
2. Set CONFIG2 bits OSCOPT[1:0] according to . The oscillator module control logic will then set OSC1 as an external clock input and, if the external crystal option is selected, OSC2 will also be set as the clock output.
3. Create a software delay to wait the stabilization time needed for the selected clock source (crystal, resonator, RC) as recommended by the component manufacturer. A good rule of thumb for crystal oscillators is to wait 4096 cycles of the crystal frequency, i.e., for a 4-MHz crystal, wait approximately 1 msec.
4. After the manufacturer's recommended delay has elapsed, the ECGON bit in the OSC status register (OSCSTAT) needs to be set by the user software.
5. After ECGON set is detected, the OSC module checks for oscillator activity by waiting two external clock rising edges.
6. The OSC module then switches to the external clock. Logic provides a glitch free transition.
7. The OSC module first sets the ECGST bit in the OSCSTAT register and then stops the internal oscillator.

NOTE

Once transition to the external clock is done, the internal oscillator will only be reactivated with reset. No post-switch clock monitor feature is implemented (clock does not switch back to internal if external clock dies).

11.3.2 External Oscillator

The external clock option is designed for use when a clock signal is available in the application to provide a clock source to the microcontroller. The OSC1 pin is enabled as an input by the oscillator module. The clock signal is used directly to create BUSCLKX4 and also divided by two to create BUSCLKX2.

In this configuration, the OSC2 pin cannot output BUSCLKX4. So the OSC2EN bit in the port A pullup enable register will be clear to enable PTA4 I/O functions on the pin

Figure 12-3 shows the port A I/O logic.

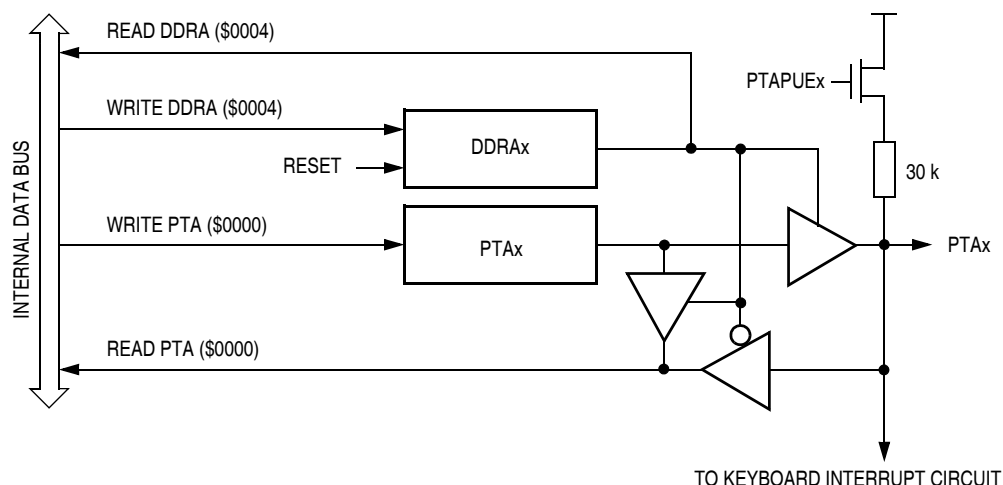


Figure 12-3. Port A I/O Circuit

NOTE

Figure 12-3 does not apply to PTA2

When DDRAx is a 1, reading address \$0000 reads the PTAx data latch. When DDRAx is a 0, reading address \$0000 reads the voltage level on the pin. The data latch can always be written, regardless of the state of its data direction bit.

12.2.3 Port A Input Pullup Enable Register

The port A input pullup enable register (PTAPUE) contains a software configurable pullup device for each of the six port A pins. Each bit is individually configurable and requires the corresponding data direction register, DDRAx, to be configured as input. Each pullup device is automatically and dynamically disabled when its corresponding DDRAx bit is configured as output.

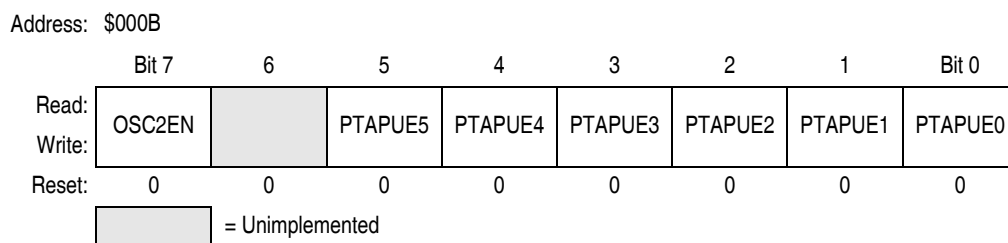


Figure 12-4. Port A Input Pullup Enable Register (PTAPUE)

OSC2EN — Enable PTA4 on OSC2 Pin

This read/write bit configures the OSC2 pin function when internal oscillator or RC oscillator option is selected. This bit has no effect for the XTAL or external oscillator options.

- 1 = OSC2 pin outputs the internal or RC oscillator clock (BUSCLKX4)
- 0 = OSC2 pin configured for PTA4 I/O, having all the interrupt and pullup functions

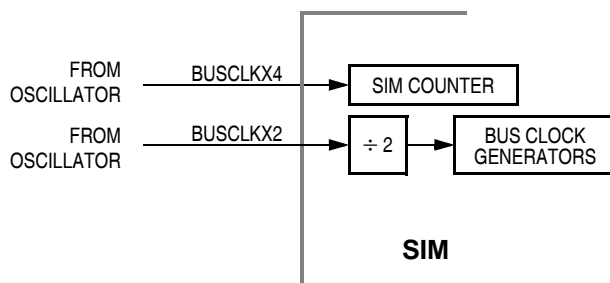


Figure 13-2. SIM Clock Signals

13.3.1 Bus Timing

In user mode, the internal bus frequency is the oscillator frequency (BUSCLKX4) divided by four.

13.3.2 Clock Start-Up from POR

When the power-on reset module generates a reset, the clocks to the CPU and peripherals are inactive and held in an inactive phase until after the 4096 BUSCLKX4 cycle POR time out has completed. The IBUS clocks start upon completion of the time out.

13.3.3 Clocks in Stop Mode and Wait Mode

Upon exit from stop mode by an interrupt or reset, the SIM allows BUSCLKX4 to clock the SIM counter. The CPU and peripheral clocks do not become active until after the stop delay time out. This time out is selectable as 4096 or 32 BUSCLKX4 cycles. See [13.7.2 Stop Mode](#).

In wait mode, the CPU clocks are inactive. The SIM also produces two sets of clocks for other modules. Refer to the wait mode subsection of each module to see if the module is active or inactive in wait mode. Some modules can be programmed to be active in wait mode.

13.4 Reset and System Initialization

The MCU has these reset sources:

- Power-on reset module (POR)
- External reset pin (\overline{RST})
- Computer operating properly module (COP)
- Low-voltage inhibit module (LVI)
- Illegal opcode
- Illegal address

All of these resets produce the vector \$FFFE–FFFF (\$FEFE–FEFF in monitor mode) and assert the internal reset signal (IRST). IRST causes all registers to be returned to their default values and all modules to be returned to their reset states.

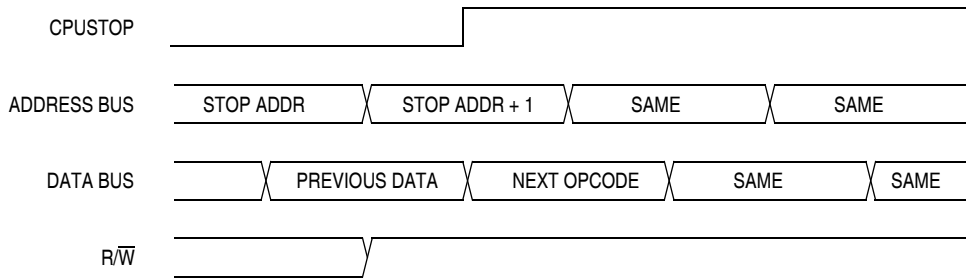
An internal reset clears the SIM counter (see [13.5 SIM Counter](#)), but an external reset does not. Each of the resets sets a corresponding bit in the SIM reset status register (SRSR). See [13.8 SIM Registers](#).

System Integration Module (SIM)

The SIM counter is held in reset from the execution of the STOP instruction until the beginning of stop recovery. It is then used to time the recovery period. [Figure 13-17](#) shows stop mode entry timing and [Figure 13-18](#) shows the stop mode recovery time from interrupt or break.

NOTE

To minimize stop current, all pins configured as inputs should be driven to a logic 1 or logic 0.



NOTE: Previous data can be operand data or the STOP opcode, depending on the last instruction.

Figure 13-17. Stop Mode Entry Timing

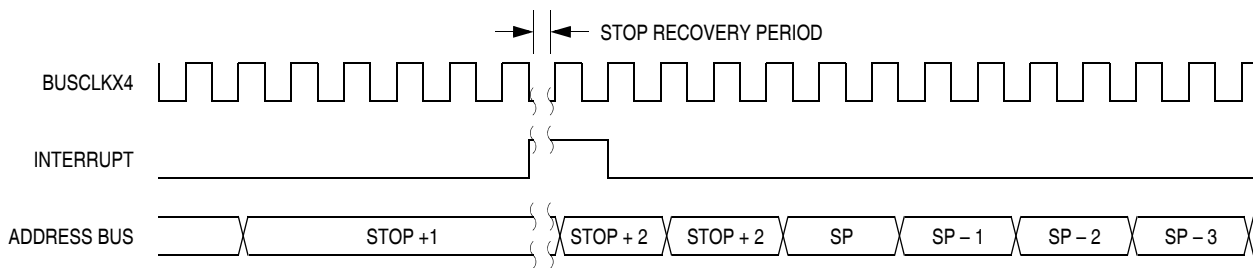


Figure 13-18. Stop Mode Recovery from Interrupt

13.8 SIM Registers

The SIM has three memory mapped registers. [Table 13-4](#) shows the mapping of these registers.

Table 13-4. SIM Registers

Address	Register	Access Mode
\$FE00	BSR	User
\$FE01	SRSR	User
\$FE03	BFCR	User

14.6 Wait Mode

The WAIT instruction puts the MCU in low power-consumption standby mode.

The TIM remains active after the execution of a WAIT instruction. In wait mode the TIM registers are not accessible by the CPU. Any enabled CPU interrupt request from the TIM can bring the MCU out of wait mode.

If TIM functions are not required during wait mode, reduce power consumption by stopping the TIM before executing the WAIT instruction.

14.7 TIM During Break Interrupts

A break interrupt stops the TIM counter.

The system integration module (SIM) controls whether status bits in other modules can be cleared during the break state. The BCFE bit in the break flag control register (BFCR) enables software to clear status bits during the break state. See [13.8.2 Break Flag Control Register](#).

To allow software to clear status bits during a break interrupt, write a 1 to the BCFE bit. If a status bit is cleared during the break state, it remains cleared when the MCU exits the break state.

To protect status bits during the break state, write a 0 to the BCFE bit. With BCFE at 0 (its default state), software can read and write I/O registers during the break state without affecting status bits. Some status bits have a two-step read/write clearing procedure. If software does the first step on such a bit before the break, the bit cannot change during the break state as long as BCFE is at 0. After the break, doing the second step clears the status bit.

14.8 Input/Output Signals

Port A shares three of its pins with the TIM. Two TIM channel I/O pins are PTA0/TCH0 and PTA1/TCH1 and an alternate clock source is PTA2/TCLK.

14.8.1 TIM Clock Pin (PTA2/TCLK)

PTA2/TCLK is an external clock input that can be the clock source for the TIM counter instead of the prescaled internal bus clock. Select the PTA2/TCLK input by writing 1s to the three prescaler select bits, PS[2–0]. (See [14.9.1 TIM Status and Control Register](#).) When the PTA2/TCLK pin is the TIM clock input, it is an input regardless of port pin initialization.

14.8.2 TIM Channel I/O Pins (PTA0/TCH0 and PTA1/TCH1)

Each channel I/O pin is programmable independently as an input capture pin or an output compare pin. PTA0/TCH0 can be configured as a buffered output compare or buffered PWM pin.

14.9 Input/Output Registers

The following I/O registers control and monitor operation of the TIM:

- TIM status and control register (TSC)
- TIM counter registers (TCNTH:TCNTL)
- TIM counter modulo registers (TMODH:TMODL)
- TIM channel status and control registers (TSC0 and TSC1)
- TIM channel registers (TCH0H:TCH0L and TCH1H:TCH1L)

CHxMAX — Channel x Maximum Duty Cycle Bit

When the TOVx bit is at a 1, setting the CHxMAX bit forces the duty cycle of buffered and unbuffered PWM signals to 100%. As Figure 14-8 shows, the CHxMAX bit takes effect in the cycle after it is set or cleared. The output stays at the 100% duty cycle level until the cycle after CHxMAX is cleared.

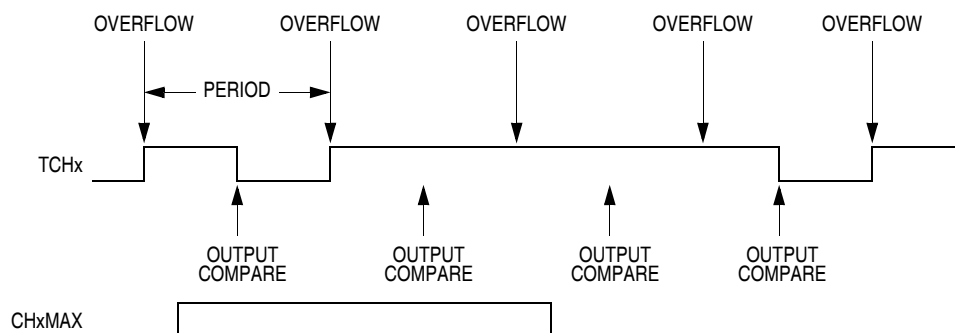


Figure 14-8. CHxMAX Latency

14.9.5 TIM Channel Registers

These read/write registers contain the captured TIM counter value of the input capture function or the output compare value of the output compare function. The state of the TIM channel registers after reset is unknown.

In input capture mode ($MSxB:MSxA = 0:0$), reading the high byte of the TIM channel x registers (TCHxH) inhibits input captures until the low byte (TCHxL) is read.

In output compare mode ($MSxB:MSxA \neq 0:0$), writing to the high byte of the TIM channel x registers (TCHxH) inhibits output compares until the low byte (TCHxL) is written.

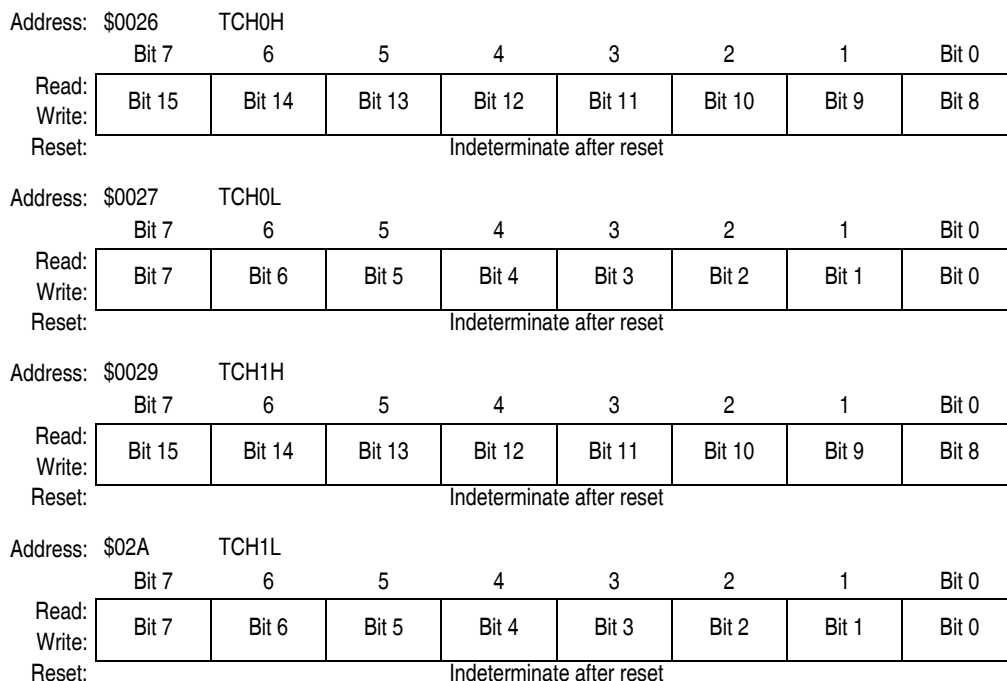


Figure 14-9. TIM Channel Registers (TCH0H/L:TCH1H/L)

Table 15-4. WRITE (Write Memory) Command

Description	Write byte to memory
Operand	2-byte address in high-byte:low-byte order; low byte followed by data byte
Data Returned	None
Opcode	\$49
Command Sequence	

Table 15-5. IREAD (Indexed Read) Command

Description	Read next 2 bytes in memory from last address accessed
Operand	None
Data Returned	Returns contents of next two addresses
Opcode	\$1A
Command Sequence	

Table 15-6. IWRITE (Indexed Write) Command

Description	Write to last address accessed + 1
Operand	Single data byte
Data Returned	None
Opcode	\$19
Command Sequence	

A sequence of IREAD or IWRITE commands can access a block of memory sequentially over the full 64-Kbyte memory map.

15.3.2 Security

A security feature discourages unauthorized reading of FLASH locations while in monitor mode. The host can bypass the security feature at monitor mode entry by sending eight security bytes that match the bytes at locations \$FFF6–\$FFFD. Locations \$FFF6–\$FFFD contain user-defined data.

NOTE

Do not leave locations \$FFF6–\$FFFD blank. For security reasons, program locations \$FFF6–\$FFFD even if they are not used for vectors.

During monitor mode entry, the MCU waits after the power-on reset for the host to send the eight security bytes on pin PTA0. If the received bytes match those at locations \$FFF6–\$FFFD, the host bypasses the security feature and can read all FLASH locations and execute code from FLASH. Security remains bypassed until a power-on reset occurs. If the reset was not a power-on reset, security remains bypassed and security code entry is not required. See [Figure 15-18](#).

Upon power-on reset, if the received bytes of the security code do not match the data at locations \$FFF6–\$FFFD, the host fails to bypass the security feature. The MCU remains in monitor mode, but reading a FLASH location returns an invalid value and trying to execute code from FLASH causes an illegal address reset. After receiving the eight security bytes from the host, the MCU transmits a break character, signifying that it is ready to receive a command.

NOTE

The MCU does not transmit a break character until after the host sends the eight security bytes.

To determine whether the security code entered is correct, check to see if bit 6 of RAM address \$80 is set. If it is, then the correct security code has been entered and FLASH can be accessed.

If the security sequence fails, the device should be reset by a power-on reset and brought up in monitor mode to attempt another entry. After failing the security sequence, the FLASH module can also be mass erased by executing an erase routine that was downloaded into internal RAM. The mass erase operation clears the security code locations so that all eight security bytes become \$FF (blank).

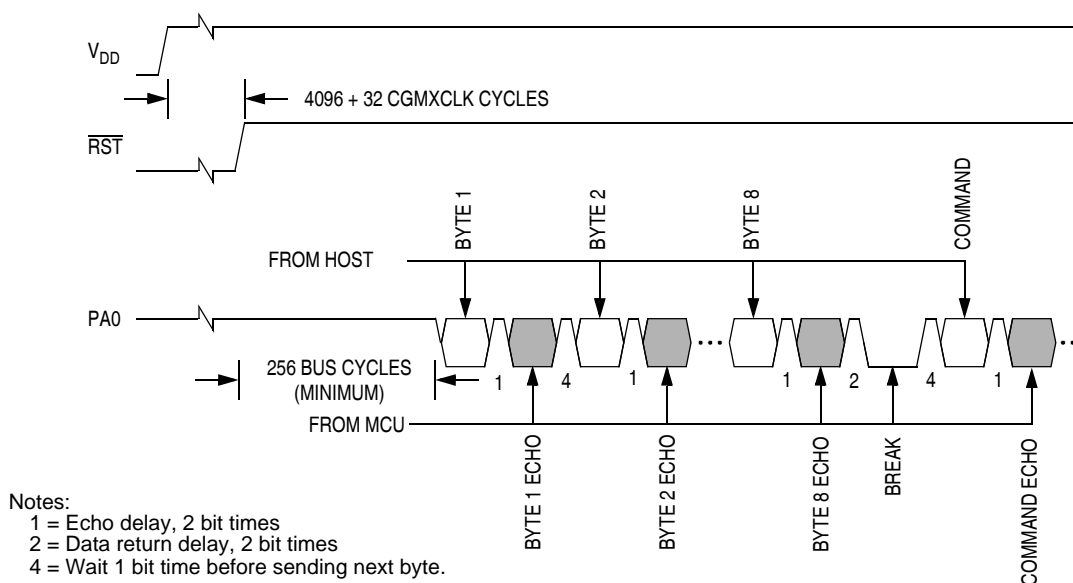


Figure 15-18. Monitor Mode Entry Timing

16.3 Functional Operating Range

Characteristic	Symbol	Value	Unit	Temp. Code
Operating temperature range	T_A	-40 to +125 -40 to +105 -40 to +85	•C	M V C
Operating voltage range	V_{DD}	2.7 to 5.5	V	—

16.4 Thermal Characteristics

Characteristic	Symbol	Value	Unit
Thermal resistance 8-pin PDIP 8-pin SOIC 8-pin DFN 16-pin PDIP 16-pin SOIC 16-pin TSSOP	θ_{JA}	105 142 173 76 90 133	•C/W
I/O pin power dissipation	$P_{I/O}$	User determined	W
Power dissipation ⁽¹⁾	P_D	$P_D = (I_{DD} \times V_{DD})$ $+ P_{I/O} = K/(T_J + 273 \cdot C)$	W
Constant ⁽²⁾	K	$P_D \times (T_A + 273 \cdot C)$ $+ P_D^2 \times \theta_{JA}$	W/•C
Average junction temperature	T_J	$T_A + (P_D \times \theta_{JA})$	•C
Maximum junction temperature	T_{JM}	150	•C

1. Power dissipation is a function of temperature.
2. K constant unique to the device. K can be determined for a known T_A and measured P_D . With this value of K, P_D and T_J can be determined for any value of T_A .

16.15 Timer Interface Module Characteristics

Characteristic	Symbol	Min	Max	Unit
Timer input capture pulse width	t_{TH}, t_{TL}	2	—	t_{cyc}
Timer input capture period	t_{TLTL}	Note ⁽¹⁾	—	t_{cyc}
Timer input clock pulse width	t_{TCL}, t_{TCH}	$t_{cyc} + 5$	—	ns

1. The minimum period is the number of cycles it takes to execute the interrupt service routine plus 1 t_{cyc} .

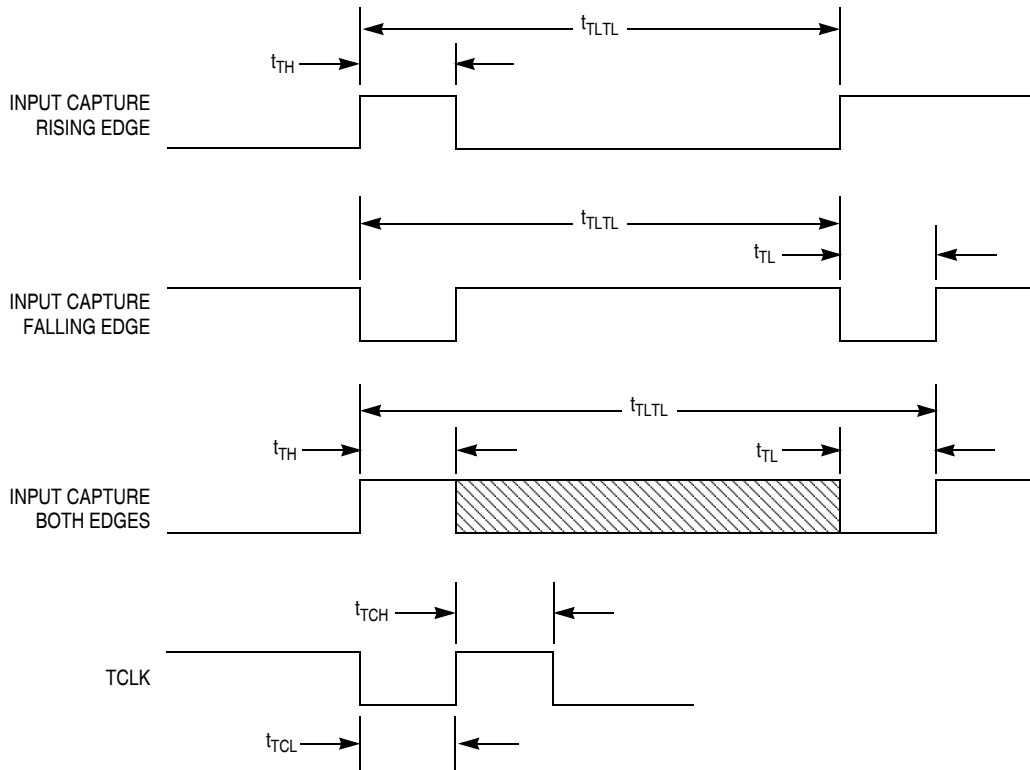
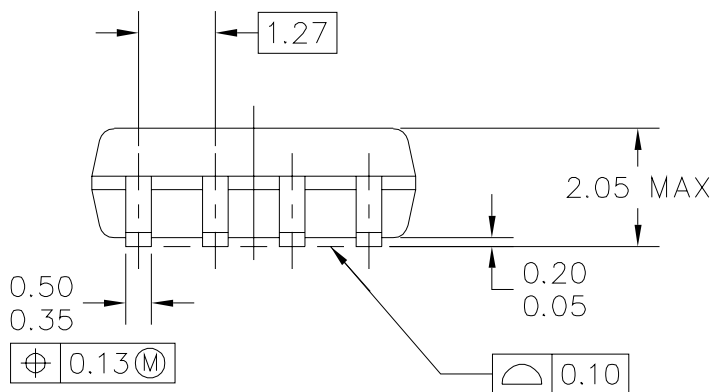
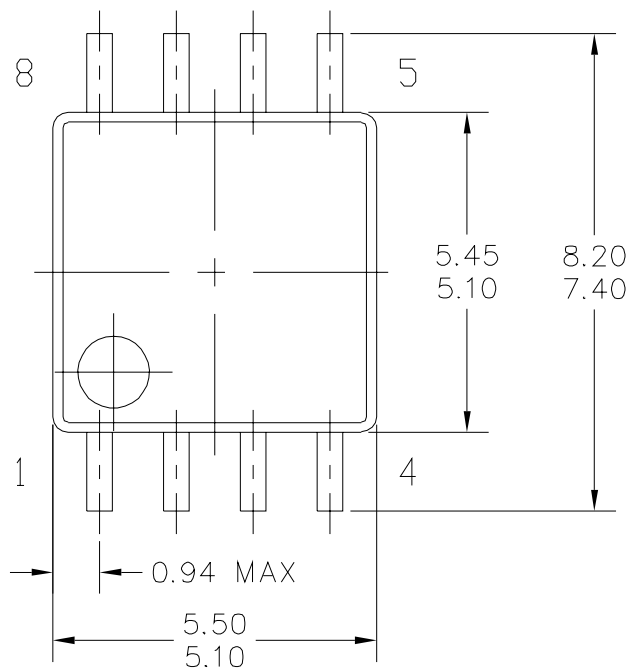


Figure 16-11. Timer Input Timing



TITLE:

8 LEAD MFP

CASE NUMBER: 968-02

STANDARD: EIAJ

PACKAGE CODE: 6003

SHEET: 1 OF 4



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**MECHANICAL OUTLINES
 DICTIONARY**


DOCUMENT NO: 98ARL10557D

PAGE: 1452

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NOTES:

1. ALL DIMENSIONS ARE IN MILLIMETERS.
2. INTERPRET DIMENSIONS AND TOLERANCES PER ASME Y14.5M-1994.
3. THE COMPLETE JEDEC DESIGNATOR FOR THIS PACKAGE IS: HP-VDFFP-N.
4.  COPLANARITY APPLIES TO LEADS AND DIE ATTACH PAD.

TITLE:THERMALLY ENHANCED DUAL
 FLAT NO LEAD PACKAGE (DFN)
 8 TERMINAL, 0.8 PITCH(4 X 4 X 1)

CASE NUMBER: 1452-01

STANDARD: NON-JEDEC

PACKAGE CODE: 6165

SHEET: 4 OF 5



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MECHANICAL OUTLINES
 DICTIONARY

DOCUMENT NO: 98ASB42431B

PAGE: 648

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REV: T

NOTES:

1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
2. CONTROLLING DIMENSION: INCH.
3. DIMENSION TO CENTER OF LEADS WHEN FORMED PARALLEL.
4. DIMENSIONS DOES NOT INCLUDE MOLD FLASH.
5. ROUNDED CORNERS OPTIONAL.
6. 648-01 THRU -08 OBSOLETE, NEW STANDARD 648-09.

DIM	MILLIMETERS		INCHES		DIM	MILLIMETERS		INCHES	
	MIN	MAX	MIN	MAX		MIN	MAX	MIN	MAX
A	18.80	19.55	0.740	0.770					
B	6.35	6.85	0.250	0.270					
C	3.69	4.44	0.145	0.175					
D	0.39	0.53	0.015	0.021					
F	1.02	1.77	0.040	0.070					
G	2.54 BSC		0.100 BSC						
H	1.27 BSC		0.050 BSC						
J	0.21	0.38	0.008	0.015					
K	2.80	3.30	0.110	0.130					
L	7.50	7.74	0.295	0.305					
M	0°	10°	0°	10°					
S	0.51	1.01	0.020	0.040					

TITLE:

16 LD PDIP

CASE NUMBER: 648-08

STANDARD: NON-JEDEC

PACKAGE CODE: 0006

SHEET: 2 OF 4